

**Preliminary Amendment**

Applicant: Wolfgang Hetzel et al.

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Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND,  
SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME

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**IN THE ABSTRACT**

Please replace the Abstract with the following rewritten paragraph:

**SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING  
COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR  
PRODUCING THE SAME**

~~The invention relates to a~~ A semiconductor device (1) with a plastic package molding compound (2), a semiconductor chip (3) and a leadframe (5) is disclosed. In one embodiment, tThe semiconductor chip (3) is embedded in a plastic package molding compound (2). The upper side of the semiconductor chip (3) and the plastic package molding compound (2) are arranged on a leadframe (4). Arranged between the leadframe (4) and the plastic package molding compound (2) with the semiconductor chip (3) is an elastic adhesive layer (11) for the mechanical decoupling of an upper region from a lower region of the semiconductor device (1).

[~~Figure 1~~]